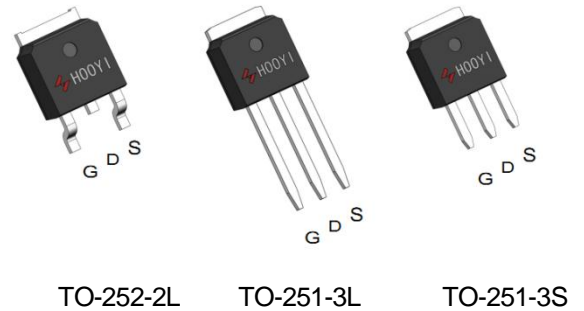


## N-Channel Enhancement Mode MOSFET

### Feature Description

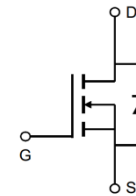
- 40V/72A  
 $R_{DS(ON)} = 4.8m\Omega (typ.) @ V_{GS} = 10V$   
 $R_{DS(ON)} = 5.8m\Omega (typ.) @ V_{GS} = 4.5V$
- 100% Avalanche Tested
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)

### Pin Description






### Applications

- Power Management for Inverter Systems



N-Channel MOSFET

### Ordering and Marking Information

 D <b>HY1904</b> YYXXXJWW G	 U <b>HY1904</b> YYXXXJWW G	 V <b>HY1904</b> YYXXXJWW G	Package Code D: TO-252-2L    U: TO-251-3L    V: TO-251-3S  Date Code YYXXX WW	Assembly Material G: Halogen Free
--	--	--	---	--------------------------------------

Note: HOOYI lead-free products contain molding compounds/die attach materials and 100% matte tin plate Termination finish; which are fully compliant with RoHS. HOOYI lead-free products meet or exceed the lead-free requirements of IPC/JEDEC J-STD-020 for MSL classification at lead-free peak reflow temperature. HOOYI defines “Green” to mean lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

HOOYI reserves the right to make changes, corrections, enhancements, modifications, and improvements to this product and/or to this document at any time without notice.

## Absolute Maximum Ratings

Symbol	Parameter		Rating	Unit
<b>Common Ratings</b> (Tc=25°C Unless Otherwise Noted)				
V <sub>DSS</sub>	Drain-Source Voltage		40	V
V <sub>GSS</sub>	Gate-Source Voltage		±20	V
T <sub>J</sub>	Maximum Junction Temperature		175	°C
T <sub>STG</sub>	Storage Temperature Range		-55 to 175	°C
I <sub>S</sub>	Source Current-Continuous(Body Diode)	Tc=25°C	72	A
<b>Mounted on Large Heat Sink</b>				
I <sub>DM</sub>	Pulsed Drain Current *	Tc=25°C	288	A
I <sub>D</sub>	Continuous Drain Current	Tc=25°C	72	A
		Tc=100°C	51	A
P <sub>D</sub>	Maximum Power Dissipation	Tc=25°C	62.5	W
		Tc=100°C	31	W
R <sub>θJC</sub>	Thermal Resistance, Junction-to-Case		2.4	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient **		110	°C/W
E <sub>AS</sub>	Single Pulsed-Avalanche Energy ***	L=0.3mH	134	mJ

Note: \* Repetitive rating; pulse width limited by max. junction temperature.  
 \*\* Surface mounted on FR-4 board.  
 \*\*\* Limited by T<sub>Jmax</sub>, starting T<sub>J</sub>=25°C, L = 0.3mH, R<sub>G</sub> = 25Ω, V<sub>GS</sub> = 10V.

## Electrical Characteristics(Tc =25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	HY1904			Unit
			Min	Typ.	Max	
<b>Static Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>DS</sub> =250μA	40	-	-	V
I <sub>DSS</sub>	Drain-to-Source Leakage Current	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V	-	-	1	μA
		T <sub>J</sub> =55°C	-	-	5	μA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250μA	1	1.7	3	V
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
R <sub>DS(ON)*</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =10V, I <sub>DS</sub> =36A	-	4.8	6.0	mΩ
		V <sub>GS</sub> =4.5V, I <sub>DS</sub> =36A	-	5.8	7.0	
<b>Diode Characteristics</b>						
V <sub>SD*</sub>	Diode Forward Voltage	I <sub>SD</sub> =36A, V <sub>GS</sub> =0V	-	0.83	1.1	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>SD</sub> =36A, dI <sub>SD</sub> /dt=100A/μs	-	53	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge		-	78	-	nC

**Electrical Characteristics (Cont.)** (T<sub>c</sub> =25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	HY1904			Unit
			Min	Typ.	Max	
<b>Dynamic Characteristics</b>						
R <sub>G</sub>	Gate Resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1 MHz	-	1.6	-	Ω
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =25V, Frequency=1.0MHz	-	2164	-	pF
C <sub>oss</sub>	Output Capacitance		-	202	-	
C <sub>rss</sub>	Reverse Transfer Capacitance		-	75	-	
t <sub>d(ON)</sub>	Turn-on Delay Time	V <sub>DD</sub> =20V, R <sub>G</sub> =4Ω, I <sub>DS</sub> =36A, V <sub>GS</sub> =10V	-	23	-	ns
T <sub>r</sub>	Turn-on Rise Time		-	28	-	
t <sub>d(OFF)</sub>	Turn-off Delay Time		-	29	-	
T <sub>f</sub>	Turn-off Fall Time		-	34	-	
<b>Gate Charge Characteristics</b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =32V, V <sub>GS</sub> =10V, I <sub>D</sub> =36A	-	51.5	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	5.5	-	
Q <sub>gd</sub>	Gate-Drain Charge		-	11	-	

Note: \*Pulse test, pulse width ≤ 300us, duty cycle ≤ 2%

## Typical Operating Characteristics

Figure 1: Power Dissipation

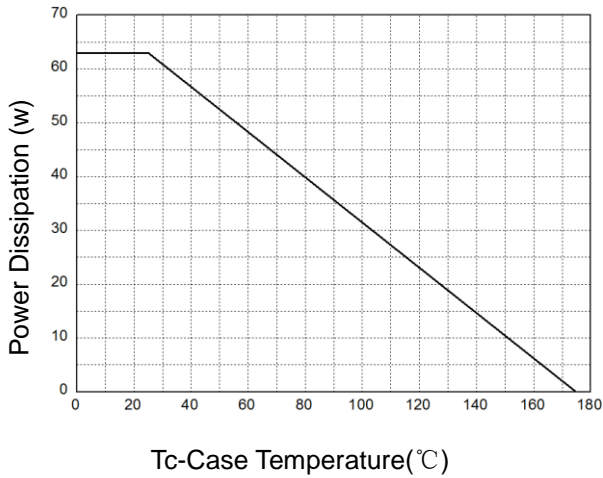


Figure 2: Drain Current

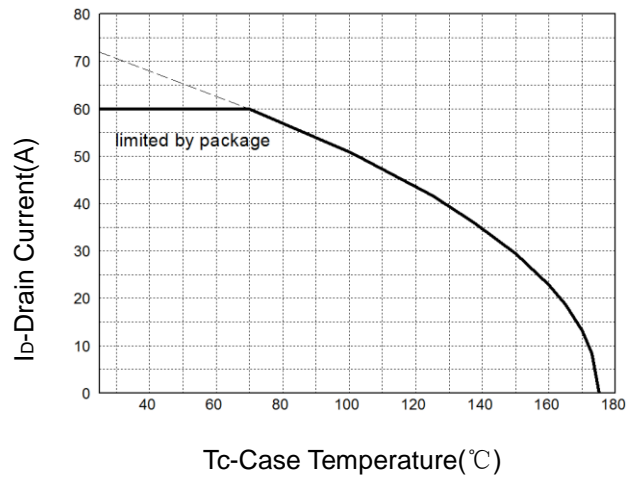


Figure 3: Safe Operation Area

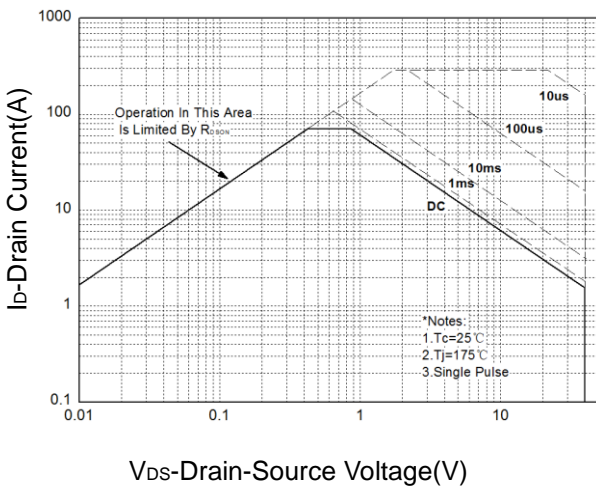


Figure 4: Thermal Transient Impedance

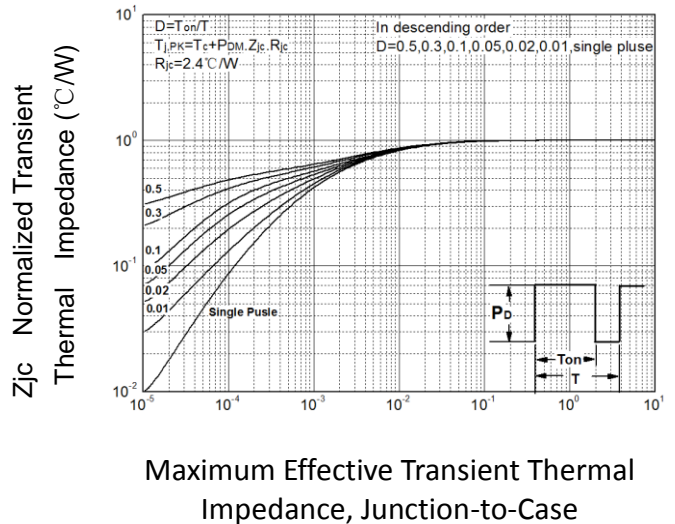


Figure 5: Output Characteristics

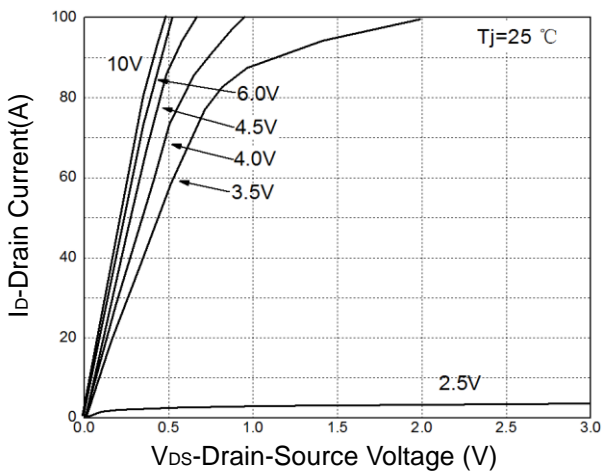
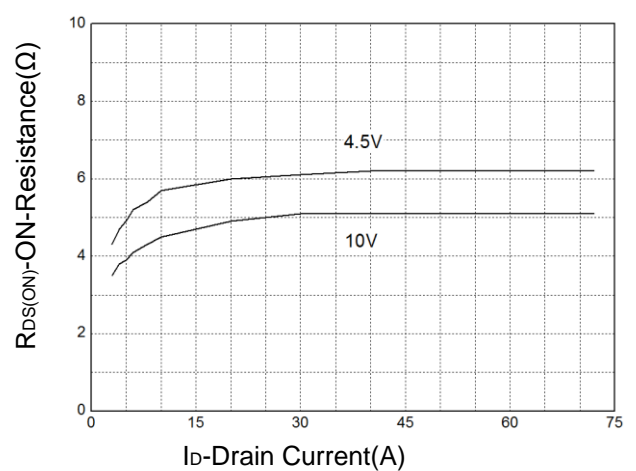
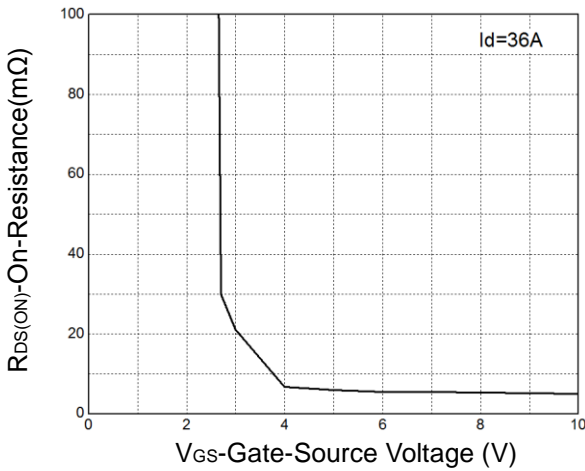


Figure 6: Drain-Source On Resistance

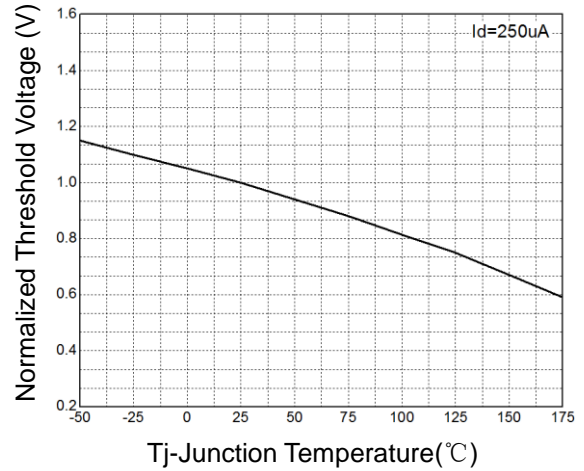


**Typical Operating Characteristics(Cont.)**

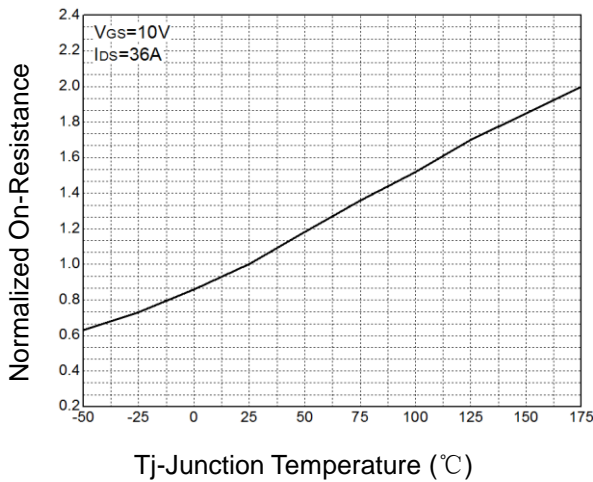
**Figure 7: Gate-Source On Resistance**



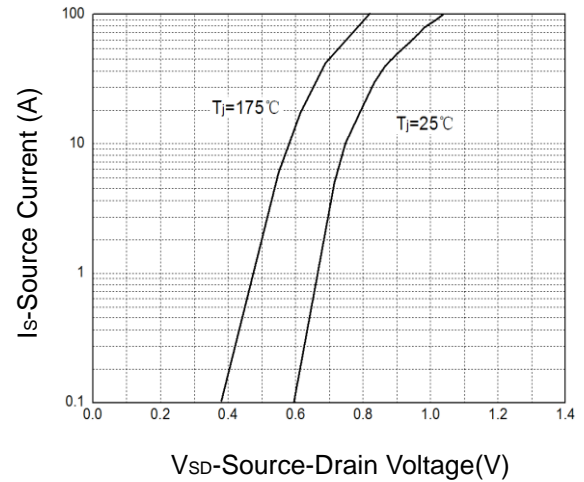
**Figure 8: Source-Drain Diode Forward**



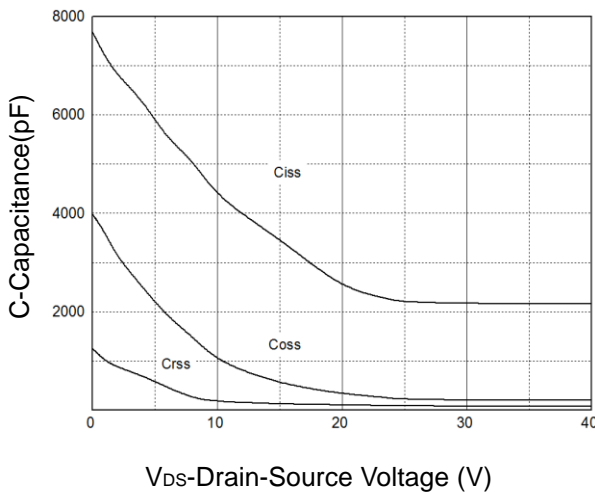
**Figure 9: On-Resistance vs. Temperature**



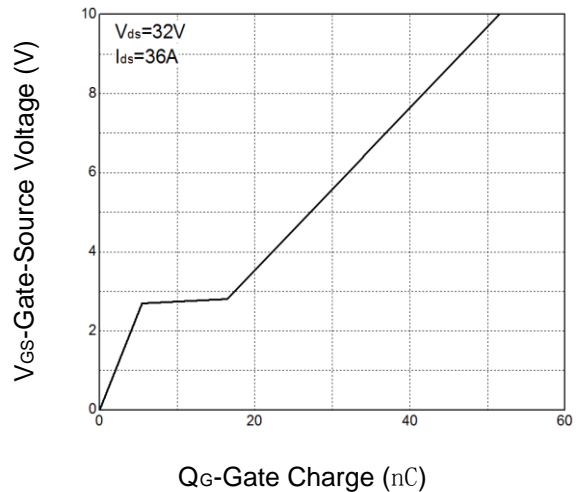
**Figure 10: Source-Drain Diode Forward**



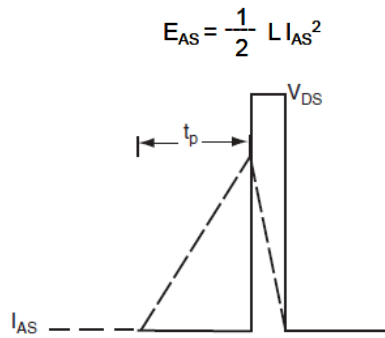
**Figure 11: Capacitance Characteristics**



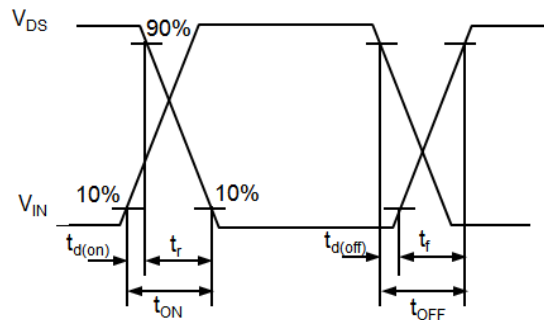
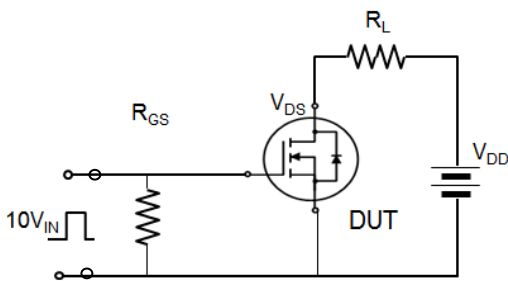
**Figure 12: Gate Charge Characteristics**



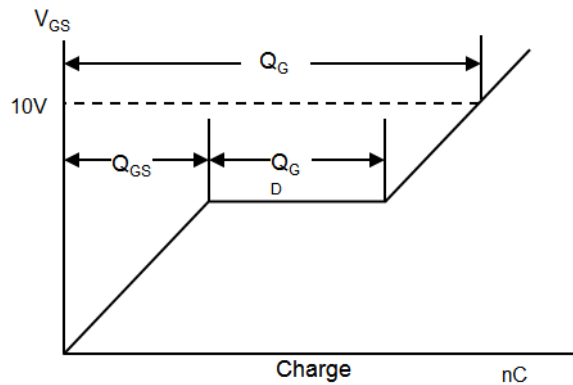
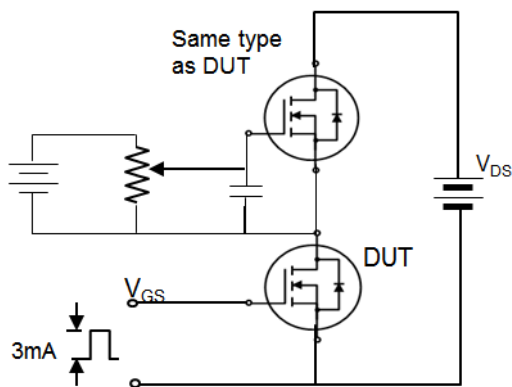
### Avalanche Test Circuit and Waveforms



### Switching Time Test Circuit and Waveforms



### Gate Charge Test Circuit and Waveforms

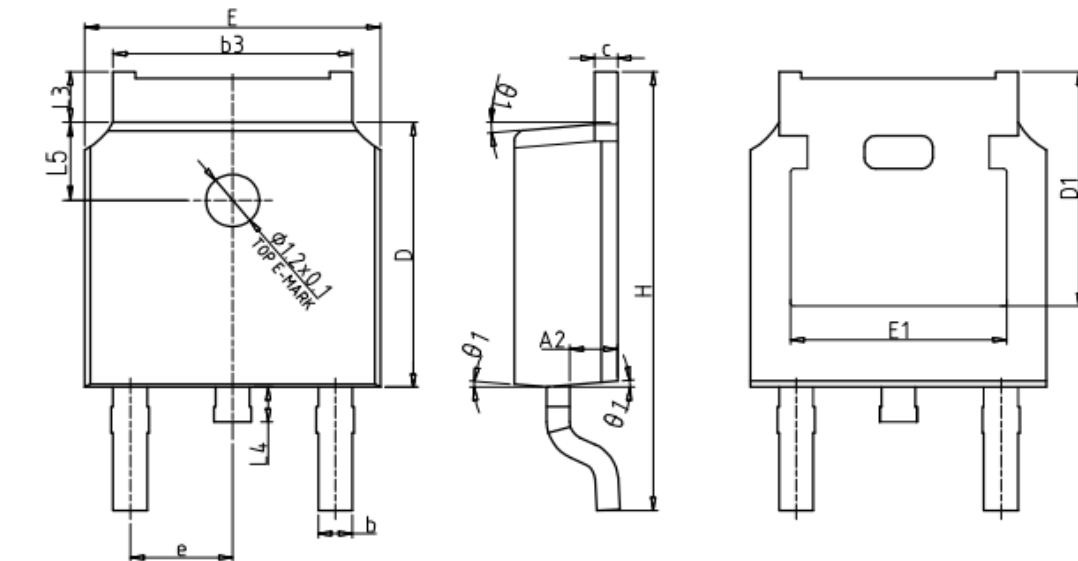


## Device Per Unit

Package Type	Unit	Quantity
TO-252-2L	Tube	75
TO-251-3L	Tube	75
TO-251-3S	Tube	75

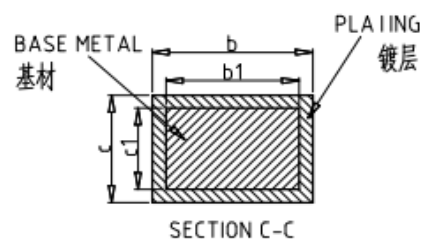
## Package Information

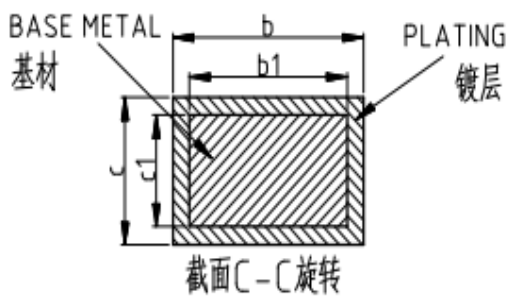
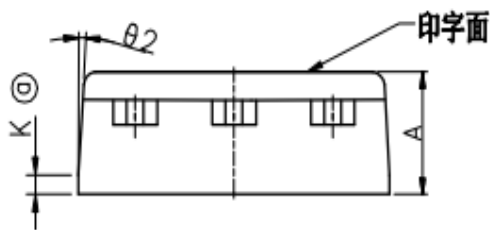
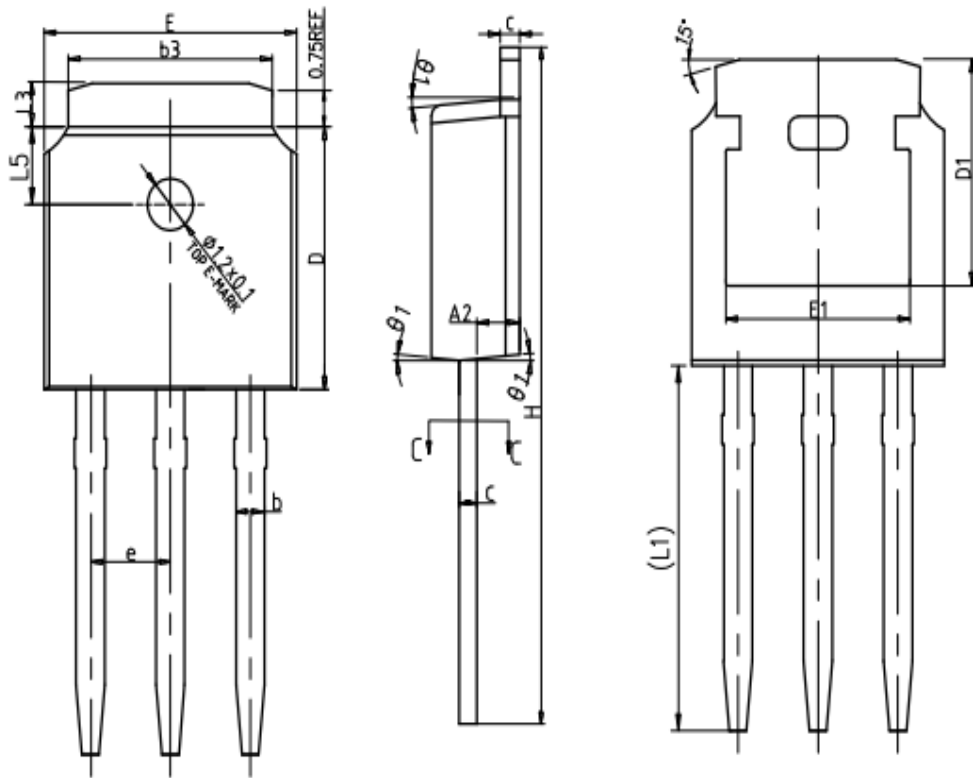
### TO-252-2L



COMMON DIMENSIONS

SYMBOL	mm		
	MIN	NOM	MAX
A	2.20	2.30	2.38
A1	0.00	-	0.10
A2	0.97	1.07	1.17
b	0.72	0.78	0.85
b1	0.71	0.76	0.81
b3	5.23	5.33	5.46
c	0.47	0.53	0.58
c1	0.46	0.51	0.56
D	6.00	6.10	6.20
D1	5.30REF		
E	6.50	6.60	6.70
E1	4.70	4.83	4.92
e	2.286BSC		
H	9.90	10.10	10.30
L	1.40	1.50	1.70
L1	2.90REF		
L2	0.51BSC		
L3	0.90	-	1.25
L4	0.60	0.80	1.00
L5	1.70	1.80	1.90
$\theta$	-		
$\theta 1$	5°	7°	9°
$\theta 2$	5°	7°	9°
K	0.40REF		

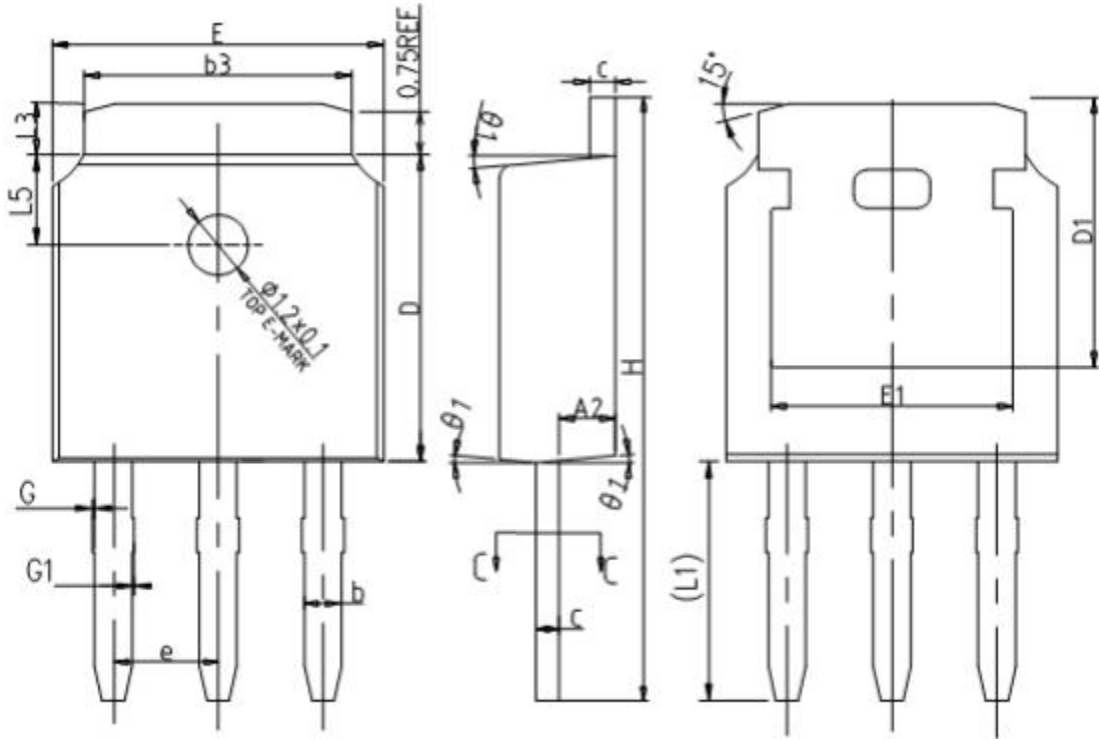




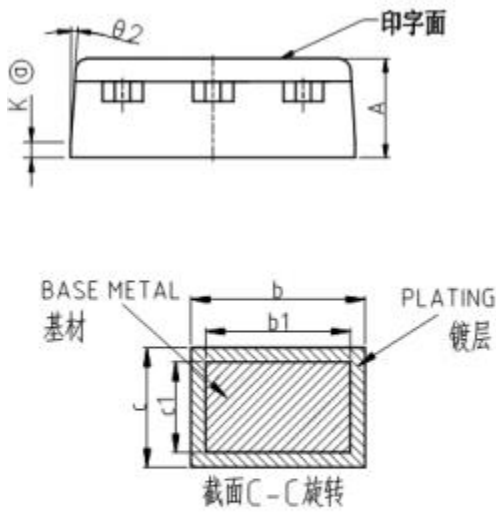
COMMON DIMENSIONS

SYMBOL	MM		
	MIN	NOM	MAX
A	2.20	2.30	2.38
A2	0.97	1.07	1.17
b	0.72	0.78	0.85
b1	0.71	0.76	0.81
b3	5.23	5.33	5.46
c	0.47	0.53	0.58
c1	0.46	0.51	0.56
D	6.00	6.10	6.20
D1	5.30REF		
E	6.50	6.60	6.70
E1	4.70	4.83	4.92
e	2.286BSC		
H	16.10	16.40	16.60
L1	9.20	9.40	9.60
L3	0.90	1.02	1.25
L5	1.70	1.80	1.90
theta 1	5°	7°	9°
theta 2	5°	7°	9°
K	0.40REF		



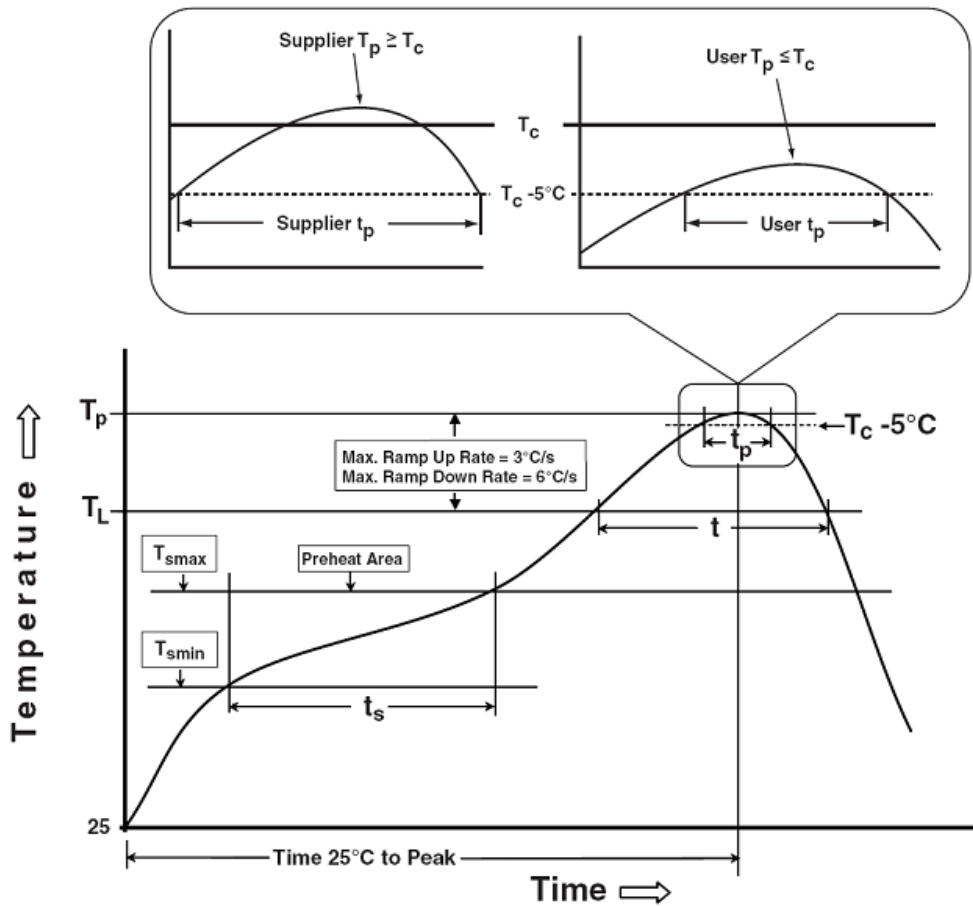


### COMMON DIMENSIONS



SYMBOL	MM		
	MIN	NOM	MAX
A	2.20	2.30	2.38
A2	0.97	1.07	1.17
b	0.72	0.78	0.85
b1	0.71	0.76	0.81
b3	5.23	5.33	5.46
c	0.47	0.53	0.58
c1	0.46	0.51	0.56
D	6.00	6.10	6.20
D1	5.30REF		
E	6.50	6.60	6.70
E1	4.70	4.83	4.92
e	2.286BSC		
H	10.00	11.20	11.40
L1	4.00	4.10	4.20
L3	0.90	1.02	1.25
L5	1.70	1.80	1.90
theta 1	5°	7°	9°
theta 2	5°	7°	9°
K	0.3	0.4	0.5

**Classification Profile**



**Classification Reflow Profiles**

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
<b>Preheat &amp; Soak</b>		
Temperature min ( $T_{smin}$ )	100 °C	150 °C
Temperature max ( $T_{smax}$ )	150 °C	200 °C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds	60-120 seconds
Average ramp-up rate ( $T_{smax}$ to $T_p$ )	3 °C/second max.	3°C/second max.
Liquidous temperature ( $T_L$ )	183 °C	217 °C
Time at liquidous ( $t_l$ )	60-150 seconds	60-150 seconds
Peak package body Temperature ( $T_p$ )*	See Classification Temp in table 1	See Classification Temp in table 2
Time ( $t_p$ )** within 5°C of the specified classification temperature ( $T_c$ )	20** seconds	30** seconds
Average ramp-down rate ( $T_p$ to $T_{smax}$ )	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.

\*Tolerance for peak profile Temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.

\*\* Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum.

Table 1. SnPb Eutectic Process – Classification Temperatures (Tc)

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures (Tc)

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350-2000	Volume mm <sup>3</sup> ≥2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

## Reliability Test Program

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HTRB	JESD-22, A108	1000 Hrs, Bias @ 125°C
PCT	JESD-22, A102	168 Hrs, 100%RH, 2atm, 121°C
TCT	JESD-22, A104	500 Cycles, -65°C~150°C

### Customer Service

Worldwide Sales and Service: sales@hooyi.cc

Technical Support: technical @ hooyi.cc

Xi'an Hooyi Semiconductor Technology Co., Ltd.

No.105, 5th Fengcheng Road, Economic and Technological Development Zone, Xi'an, China

TEL: (86-029) 86685706

FAX: (86-029) 86685705

E-mail: sales@hooyi.cc

Web net: www.hooyi.cc